

**IDENTIFIKASI PENYEBAB KEMASAN *REJECT* MENGGUNAKAN
DIAGRAM PARETO DAN DIAGRAM ISIKHAWA DI PT XYZ,
TANGERANG, BANTEN**

Oleh:

Aprilianawati¹, Diklusari Isnarosi Norsita², Moh. Affan Falah³, Sri Wijanarti⁴

RINGKASAN

PT XYZ perusahaan yang bergerak di bidang *snack* atau makanan ringan. PT XYZ beralamat di kawasan industri Cikupa Mas jalan Bhumi mas II No. 5 RT 01 RW 03 Cikupa Mas Tangerang. PT XYZ memiliki Departemen *Quality Control* yang bertugas melakukan pemeriksaan dan memastikan mutu yang dihasilkan oleh bahan baku, proses produksi, dan distribusi sesuai *standard* SNI, ISO 22000, HACCP, SOP, GMP, PHC, dan RMHC. Departemen *Quality Control* memiliki permasalahan yaitu kemasan *reject* lolos dan terdistribusikan. Kemasan yang dinyatakan kemasan *reject* yaitu kode produksi hilang, *backseal* kemasan berkerut, *backseal* kemasan terlipat, *endseal* kemasan berkerut, kemasan kempis dan *cutting* tidak rapi. Kemasan *reject* yang dihasilkan memiliki presentase 1,01 %. Tujuan dari magang ini adalah mengetahui jenis kemasan *reject* produk Kripik Kentang a, Kripik Kentang b dan Tortilla Chips yang dominan, mengetahui penyebab kemasan *reject* pada produk Kripik Kentang a, Kripik Kentang b, dan Tortilla Chips. Pengambilan data dengan melakukan wawancara karyawan PT XYZ. Hasil: kemasan *reject* diurutkan berdasarkan nilai tertinggi kemasan *reject* dengan menggunakan Diagram Pareto yaitu *cutting* tidak rapi (30%), *backseal* kemasan berkerut (28%), *endseal* kemasan berkerut (16%), kemasan kempis (13%), kemasan hilang kode produksi (8%) dan *backseal* kemasan terlipat (6%). Selanjutnya analisis menggunakan Diagram Isikhawa yaitu faktor-faktor yang menyebabkan kemasan Kripik Kentang a, Kripik Kentang b dan Tortilla Chips menjadi *reject* diantaranya faktor *method* disebabkan oleh penerapan *standard* kemasan belum maksimal. Faktor *man* disebabkan oleh pekerja kurang teliti, pekerja mengalami kejenuhan dan pekerja dikejar target produksi. Faktor *machine* disebabkan mesin rusak, mesin mengalami panas, faktor *material* disebabkan oleh film PVC rusak, tinta habis, dan nitrogen. Faktor *enviroment* disebabkan oleh jarak mesin *automatic weighing* dengan mesin *packing* terlalu dekat

Kata kunci: Diagram Pareto, Diagram Isikhawa, *Kemasan reject*, *Machine Vision*, dan PT XYZ

Mahasiswa Agroindustri, Departemen THV, SV, Universitas Gadjah Mada¹

Dosen Agroindustri, Departemen THV, SV, Universitas Gadjah Mada²

**IDENTIFY THE CAUSE OF REJECT PACKAGING USING PARETO
DIAGRAM AND ISIKHAWA DIAGRAM IN PT XYZ, TANGERANG,
BANTEN**

Author:

Aprilianawati¹, Diklusari Isnarosi Norsita², Moh. Affan Falah³, Sri Wijanarti⁴

SUMMARY

PT XYZ is a company engaged in the field of snacks or snacks. PTXYZ is located in Cikupa Mas industrial area Jalan Bhumi mas II No. 5 RT 01 RW 03 Cikupa Mas Tangerang. PT XYZ has a Quality Control Department that is tasked with inspecting and ensuring the quality produced by raw materials, production processes, and distribution according to SNI, ISO 22000, HACCP, SOP, GMP, PHC, and RMHC standards. The Quality Control Department has a problem on reject packaging. The packages that were declared reject packaging were unclear production codes, wrinkled backseal packaging, folded backseal packaging, wrinkled endseal packaging, deflated packaging and sloppy cutting. The reject packaging percentage was 1.01%. The purpose of this was to find out the dominant type of reject packaging for Potato Chips a, Potato Chips b and Tortilla Chips, to find out the causes of reject packaging in Potato Chips a, Potato Chips b, and Tortilla Chips products. Data were collected from interviews with PT XYZ employees. Results: reject packaging is sorted according to the highest value of reject packaging using Pareto Diagrams, namely sloppy cutting (30%), backseal wrinkled packaging (28%), endseal wrinkled packaging (16%), deflated packaging (13%), lost packaging production code (8%) and folded backseal (6%). Furthermore, the analysis uses the Isikhawa diagram, namely the factors that cause Potato Chips a, Potato Chips b and Tortilla Chips packaging to be rejected, including the method factor caused by the application of packaging standards that have not been maximal. The human factor is caused by workers who are not careful, workers experience saturation and workers are being chased by production targets. The machine factor is caused by the machine is damaged, the machine is hot, the material factor is caused by the PVC film is damaged, the ink runs out, and nitrogen. Environment factor is caused by the distance between the automatic weighing machine and the packing machine is too close

Keywords: *Pareto diagram, Isikhawa diagram, Reject packaging, Machine vision, and PT XYZ*

Student of Agroindustry, THV Department, SV, Gadjah Mada University¹

Lecturer of Agroindustry, THV Department, SV, Gadjah Mada University²